

9. A method of conductively interconnecting electronic components comprising:
providing a curable adhesive composition comprising an epoxy terminated silane
comprising a glycidoxy methoxy silane;

providing first and second electronic components to be conductively connected with
one another;

interposing the curable adhesive composition between the first and second
electronic components; and

curing the adhesive into an electrically conductive bond electrically interconnecting
the first and second components.

10. The method of claim 9 wherein at least one of the components comprises a
nickel containing metal surface over which the curable adhesive composition is received.

12. The method of claim 9 wherein the epoxy terminated silane comprises a
glycidoxypropyltrimethoxysilane.

13. The method of claim 9 wherein the epoxy terminated silane is present in the
curable adhesive composition at less than or equal to about 2% by weight.

14. The method of claim 9 wherein the epoxy terminated silane is present in the
curable adhesive composition at less than or equal to about 1% by weight.

23. A method of conductively interconnecting electronic components comprising:
interposing a curable epoxy composition between first and second electrically conductive components to be electrically interconnected, at least one of the components comprising a metal surface with which the curable epoxy is to electrically connect; and
curing the epoxy into an electrically conductive bond electrically interconnecting the first and second components, the epoxy having an effective metal surface wetting concentration of silane to form a cured electrical interconnection having a contact resistance through said metal surface of less than or equal to about 0.3 ohm-cm^2 .

24. The method of claim 23 wherein the epoxy has an effective metal surface wetting concentration of silane to form a cured electrical interconnection having a resistance through said metal surface of less than or equal to about 0.16 ohm-cm^2 .

25. The method of claim 23 wherein the epoxy has an effective metal surface wetting concentration of silane to form a cured electrical interconnection having a resistance through said metal surface of less than or equal to about 0.032 ohm-cm^2 .

26. The method of claim 23 wherein the metal surface wetting concentration of silane in the curable adhesive composition is less than or equal to about 2% by weight.

27. The method of claim 23 wherein the metal surface wetting concentration of silane in the curable adhesive composition is less than or equal to about 1% by weight.

28. The method of claim 23 wherein the metal surface comprises nickel over which the curable adhesive composition is received.

Please add the following new claims:

D1

51. (New) The method of claim 9 wherein the first electronic component comprises a first conductive node and the second electronic component comprises a second conductive node, wherein the first and second nodes comprise interfaces for the electrically interconnecting the first and second components, and wherein the interposing provides the curable adhesive composition interposed between the interfaces.

52. (New) The method of claim 51 wherein the curable adhesive composition contacts the interfaces.

53. (New) The method of claim 23 wherein the metal surface comprises a first conductive node of the first electronic component and the second electronic component comprises a second conductive node, wherein the first and second nodes comprise interfaces for the electrically interconnecting the first and second components, and wherein the interposing provides the curable epoxy composition interposed between the interfaces.

54. (New) The method of claim 53 wherein the curable epoxy composition contacts the metal surface and the second conductive node.